B2

10. (amended) The wiring substrate according to claim 6, wherein the acid anhydride curing agent, before embedding, has a viscosity at 25°C ± 1°C of not higher than 170 mPa · s.

B3

12. (amended) The wiring substrate according to claim 6, wherein the filler contains at least one inorganic filler.

IN THE ABSTRACT:

Please delete the present Abstract of the Disclosure and replace it with the following new Abstract of the Disclosure.

B4

Abstract of the Disclosure

A wiring substrate includes (1) an insulating substrate having an opening, or a core substrate and a build-up layer wherein at least one of the core substrate and the build-up layer has an opening, (2) at least one electronic part disposed in the opening, and (3) an embedding resin comprising a thermoplastic resin, an acid anhydride curing agent, a curing accelerator, and a filler, wherein the embedding resin shows a viscosity of not higher than 85 Pa · s in a shear rate of 8.4 s^{-1} after allowing to stand for 24 hours at 25°C ± 1°C.